PCN Number:	20160907002	**PCN Date:**	Sept. 9, 2016
Title:	Qualification of RFAB, NSE as additional Fab site and Assembly/Test site options for select devices		
Customer Contact:	PCN Manager	**Dept:**	Quality Services
Proposed 1st Ship Date:	Dec. 9, 2016	**Estimated Sample Availability:**	Date provided at sample request.

Change Type:

☒	Assembly Site	☒	Assembly Process	☐	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☒	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☒	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process
		☐	Part number change		

PCN Details

Description of Change:

This change notification is to announce the addition of RFAB and NSE as additional Fab site and Assembly/Test site options for select devices. Material differences as follows.

Current Fab Site			Additional Fab Site		
Current Fab Site	**Process**	**Wafer Diameter**	**Additional Fab Site**	**Process**	**Wafer Diameter**
DP1DM5	C05	200 mm	RFAB	C05	300 mm

Current Assembly Site			Additional Assembly Site		
Current	**Mount Compound**	**Mold Compound**	**Additional Assembly Site**	**Mount Compound**	**Mold Compound**
MLA	4205846	4208625	NSE	PZ0035	GZ0289

Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ. Qual details are provided in the Qual Data Section.

Reason for Change:

Capacity increase

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

☐	No Impact to the Material Declaration	☒	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained at the site link below http://www.ti.com/quality/docs/materialcontentsearch.tsp

Changes to product identification resulting from this PCN:

Fab Site:

Current Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
DP1DM5	DM5	USA	Dallas
New Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
RFAB	**RFB**	**USA**	**Richardson**

Assembly Site:

Current Assembly Site: TI Malaysia	Assembly Site Origin (22L)	ASO: MLA
New Assembly Site: UTAC Thai Limited	**Assembly Site Origin (22L)**	**ASO: NSE**

Sample product shipping label (not actual product label)

ASSEMBLY SITE CODES: MLA =K, **NSE = J**

Product Affected:

TLV320AIC3253IRGER	TLV320AIC3253IRGET	TLV320DAC3203IRGER	TLV320DAC3203IRGET

Qualification Report

TLV320AIC3253 and TLV320DAC3203
(DMOS5 TO RFAB OFFLOAD C05 - CBA477ABBB and MLA to NSE Qualification)

Approve Date 23-Aug-2016

Product Attributes

Attributes	Qual Device: TLV320AIC3253IRGER	QBS Process Reference: VSP6825BZRC	QBS Package Reference: SH6966ADU0RGCRG4	QBS Package Reference: TLV73333PQDRVRQ1
Assembly Site	NSE	PHI	NSE	NSE
Package Family	QFN	JRBGA	QFN	QFN
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	RFAB	HIJI, RFAB	UMC	RFAB
Wafer Fab Process	1833C05X4	1833C05, LBC4	LBC7	LBC7

- QBS: Qual by Similarity
- Qual Device TLV320AIC3253IRGER is qualified at LEVEL2-260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TLV320AIC3253IRGER	QBS Process Reference: VSP6825BZRC	QBS Package Reference: SH6966ADU0RGCRG4	QBS Package Reference: TLV73333PQDRVRQ1
AC	Autoclave 121C	96 Hours	-	-	3/231/0	3/231/0
ED	Electrical Characterization	Per Datasheet Parameters	Pass	-	-	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	3/230/0	3/231/0	3/231/0
HTOL	Life Test, 125C	1000 Hours	-	-	-	1/77/0
HTOL	Life Test, 140C	480 Hours	-	3/231/0	-	-
HTSL	High Temp Storage Bake 150C	1000 Hours	-	-	3/231/0	1/50/0
HTSL	High Temp Storage Bake 170C	420 Hours	-	3/231/0	-	-
PD	Physical Dimensions	(per mechanical drawing)	1/5/0	-	-	-

Type	Test Name / Condition	Duration	Qual Device: TLV320AIC3253IRGER	QBS Process Reference: VSP6825BZRC	QBS Package Reference: SH6966ADU0RGCRG4	QBS Package Reference: TLV73333PQDRVRQ1
TC	Temperature Cycle, -65/150C	500 Cycles	-	3/231/0	3/231/0	3/231/0
WBP	Bond Pull	Wires	1/76/0	-	-	-
WBS	Ball Bond Shear	Wires	1/76/0	-	-	-

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:
Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
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